

# Silicon Carbide (SiC) MOSFET – EliteSiC, 12 mohm, 650 V, M2, D2PAK-7L

## NTBG015N065SC1

### Features

- Typ.  $R_{DS(on)} = 12 \text{ m}\Omega$  @  $V_{GS} = 18 \text{ V}$   
Typ.  $R_{DS(on)} = 15 \text{ m}\Omega$  @  $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge ( $Q_{G(tot)} = 283 \text{ nC}$ )
- Low Effective Output Capacitance ( $C_{oss} = 424 \text{ pF}$ )
- 100% Avalanche Tested
- $T_J = 175^\circ\text{C}$
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

### Typical Applications

- SMPS (Switching Mode Power Supplies)
- Solar Inverters
- UPS (Uninterruptable Power Supplies)
- Energy Storages

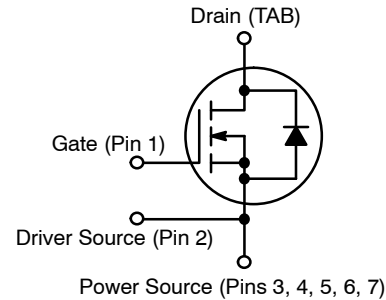
### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	650	V
Gate-to-Source Voltage			$V_{GS}$	-8/+22	V
Recommended Operation Values of Gate – Source Voltage		$T_C < 175^{\circ}\text{C}$	$V_{GSop}$	-5/+18	V
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	$T_C = 25^{\circ}\text{C}$	$I_D$	145	A
Power Dissipation $R_{\theta JC}$ (Note 2)			$P_D$	500	W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	$T_C = 100^{\circ}\text{C}$	$I_D$	103	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)			$P_D$	250	W
Pulsed Drain Current (Note 3)		$T_C = 25^{\circ}\text{C}$	$I_{DM}$	422	A
Operating Junction and Storage Temperature Range			$T_J, T_{stg}$	-55 to +175	$^{\circ}\text{C}$
Source Current (Body Diode)			$I_S$	111	A
Single Pulse Drain-to-Source Avalanche Energy ( $I_L = 13\text{ A}_{pk}$ , $L = 1\text{ mH}$ ) (Note 4)			$E_{AS}$	84	mJ
Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds			$T_L$	245	$^{\circ}\text{C}$

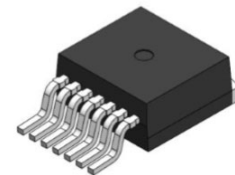
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on a FR-4 board using 1 in<sup>2</sup> pad of 2 oz copper.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. Repetitive rating, limited by max junction temperature.
4.  $E_{AS}$  of 84 mJ is based on starting  $T_J = 25^\circ\text{C}$ ;  $L = 1 \text{ mH}$ ,  $I_{AS} = 13 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $V_{GS} = 18 \text{ V}$ .

$V_{(BR)DSS}$	$R_{DS(on)} \text{ MAX}$	$I_D \text{ MAX}$
650 V	18 m $\Omega$ @ 18 V	145 A



N-CHANNEL MOSFET



D2PAK-7L  
CASE 418BJ

### MARKING DIAGRAM

BG015N  
065SC1  
AYWWZZ

BG015N065SC1 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
ZZ = Lot Traceability

### ORDERING INFORMATION

Device	Package	Shipping†
NTBG015N065SC1	D2PAK-7L	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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## THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-to-Case (Note 2)	$R_{\theta JC}$	0.3	$^{\circ}\text{C/W}$
Thermal Resistance Junction-to-Ambient (Notes 1, 2)	$R_{\theta JA}$	40	$^{\circ}\text{C/W}$

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	650			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 20\text{ mA}$ , refer to $25^{\circ}\text{C}$		0.12		$\text{V}/^{\circ}\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V},$ $V_{DS} = 650\text{ V}$	$T_J = 25^{\circ}\text{C}$		10	$\mu\text{A}$
			$T_J = 175^{\circ}\text{C}$		1	$\text{mA}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS} = +22/-8\text{ V}, V_{DS} = 0\text{ V}$			250	$\text{nA}$

### ON CHARACTERISTICS

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 25\text{ mA}$	1.8	2.8	4.3	V
Recommended Gate Voltage	$V_{GOP}$		-5		+18	V
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 15\text{ V}, I_D = 75\text{ A}, T_J = 25^{\circ}\text{C}$		15		$\text{m}\Omega$
		$V_{GS} = 18\text{ V}, I_D = 75\text{ A}, T_J = 25^{\circ}\text{C}$		12	18	
		$V_{GS} = 18\text{ V}, I_D = 75\text{ A}, T_J = 175^{\circ}\text{C}$		16		
Forward Transconductance	$g_{FS}$	$V_{DS} = 10\text{ V}, I_D = 75\text{ A}$		42		S

### CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz},$ $V_{DS} = 325\text{ V}$		4689		$\text{pF}$
Output Capacitance	$C_{OSS}$			424		
Reverse Transfer Capacitance	$C_{RSS}$			37		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -5/18\text{ V}, V_{DS} = 520\text{ V},$ $I_D = 75\text{ A}$		283		$\text{nC}$
Gate-to-Source Charge	$Q_{GS}$			72		
Gate-to-Drain Charge	$Q_{GD}$			64		
Gate-Resistance	$R_G$	$f = 1\text{ MHz}$		1.6		$\Omega$

### SWITCHING CHARACTERISTICS

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -5/18\text{ V}, V_{DS} = 400\text{ V},$ $I_D = 75\text{ A}, R_G = 2.2\text{ }\Omega,$ Inductive Load		23		$\text{ns}$
Rise Time	$t_r$			26		
Turn-Off Delay Time	$t_{d(OFF)}$			49		
Fall Time	$t_f$			9.6		
Turn-On Switching Loss	$E_{ON}$			167		$\mu\text{J}$
Turn-Off Switching Loss	$E_{OFF}$			276		
Total Switching Loss	$E_{TOT}$			443		

### DRAIN-SOURCE DIODE CHARACTERISTICS

Continuous Drain-Source Diode Forward Current	$I_{SD}$	$V_{GS} = -5\text{ V}, T_J = 25^{\circ}\text{C}$			111	A
Pulsed Drain-Source Diode Forward Current (Note 3)	$I_{SDM}$	$V_{GS} = -5\text{ V}, T_J = 25^{\circ}\text{C}$			422	A
Forward Diode Voltage	$V_{SD}$	$V_{GS} = -5\text{ V}, I_{SD} = 75\text{ A}, T_J = 25^{\circ}\text{C}$		4.8		V

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## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)(continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### DRAIN-SOURCE DIODE CHARACTERISTICS

Reverse Recovery Time	$t_{RR}$	$V_{GS} = -5/18\text{ V}, I_{SD} = 75\text{ A},$ $dI_S/dt = 1000\text{ A}/\mu\text{s}$		28		ns
Reverse Recovery Charge	$Q_{RR}$			234		nC
Reverse Recovery Energy	$E_{REC}$			23		$\mu\text{J}$
Peak Reverse Recovery Current	$I_{RRM}$			16		A
Charge Time	$T_a$			17		ns
Discharge Time	$T_b$			11		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

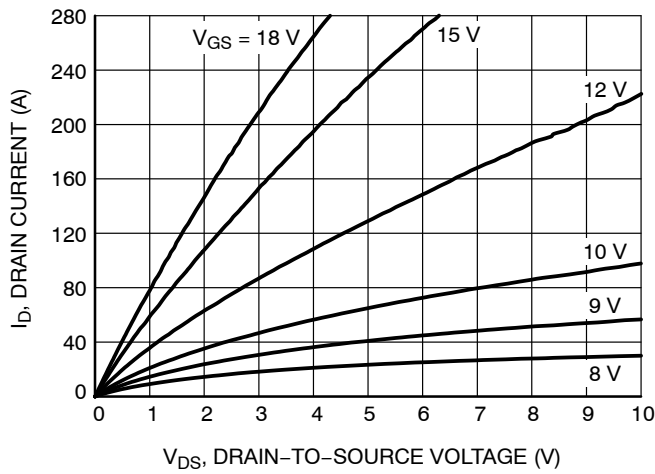


Figure 1. On-Region Characteristics

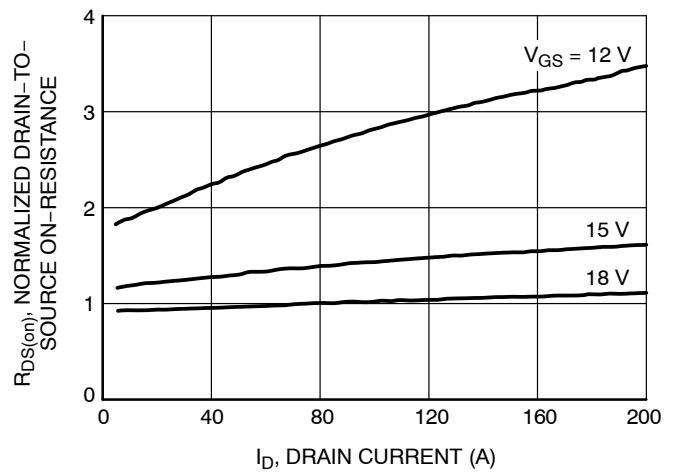


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

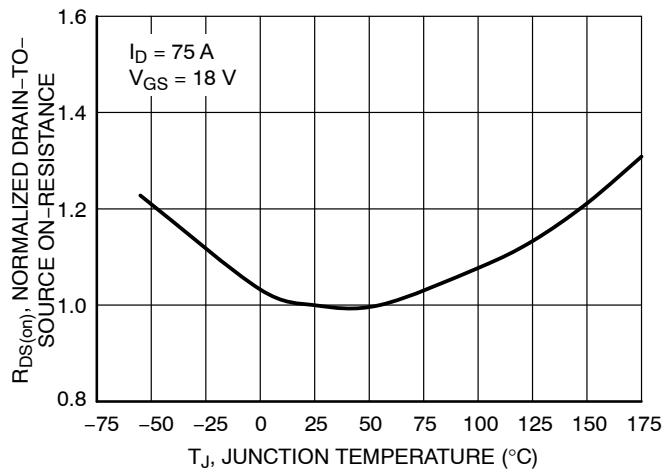


Figure 3. On-Resistance Variation with Temperature

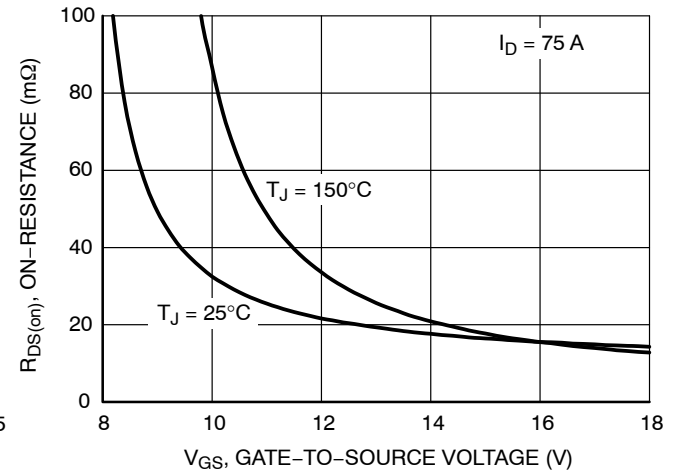


Figure 4. On-Resistance vs. Gate-to-Source Voltage

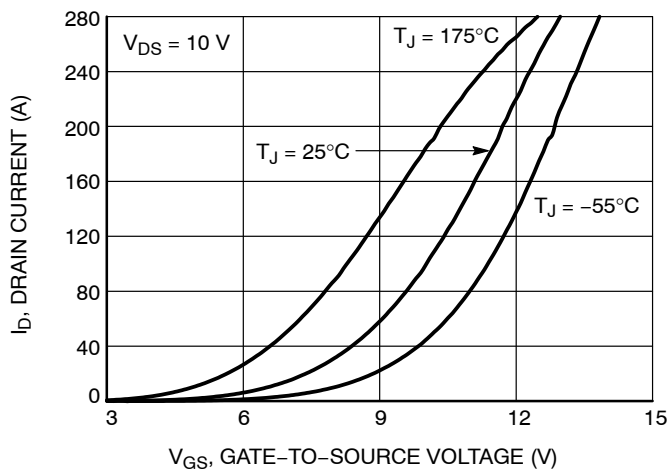


Figure 5. Transfer Characteristics

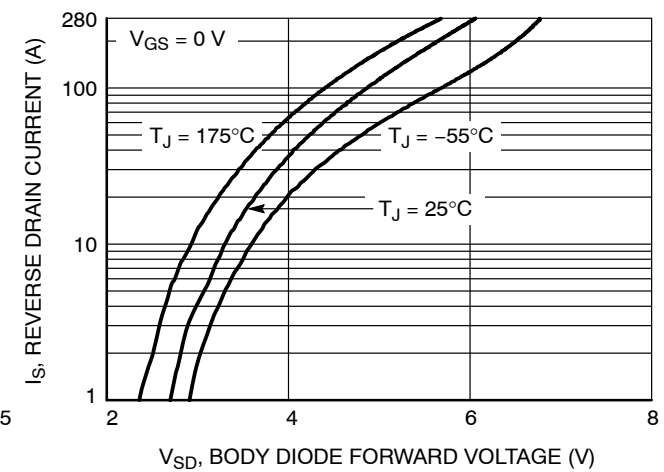


Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS (continued)

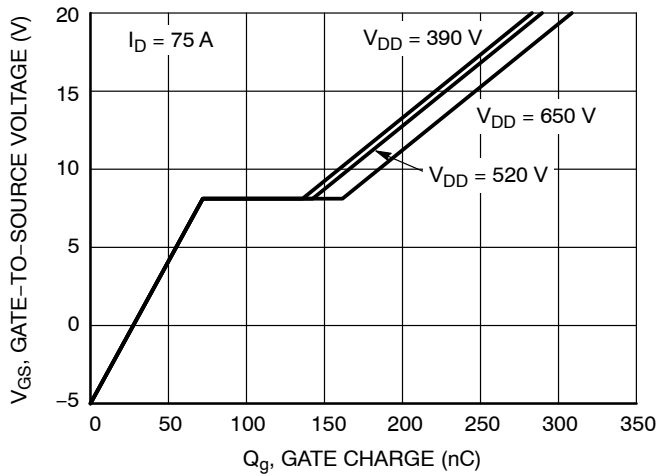


Figure 7. Gate-to-Source Voltage vs. Total Charge

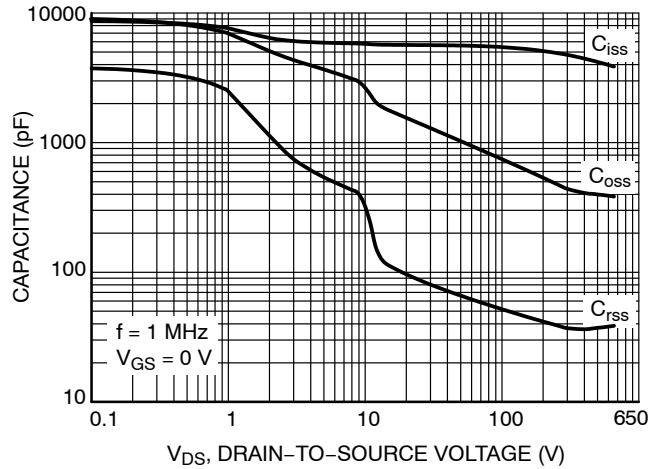


Figure 8. Capacitance vs. Drain-to-Source Voltage

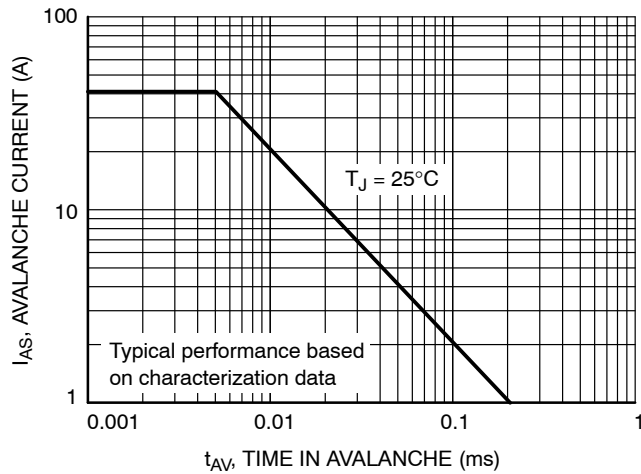


Figure 9. Unclamped Inductive Switching Capability

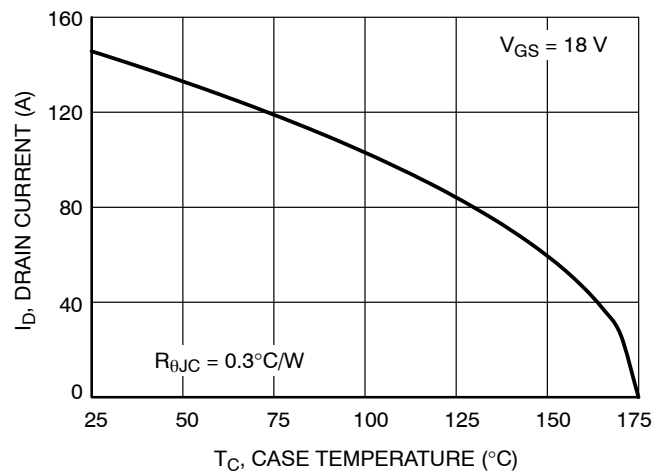


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

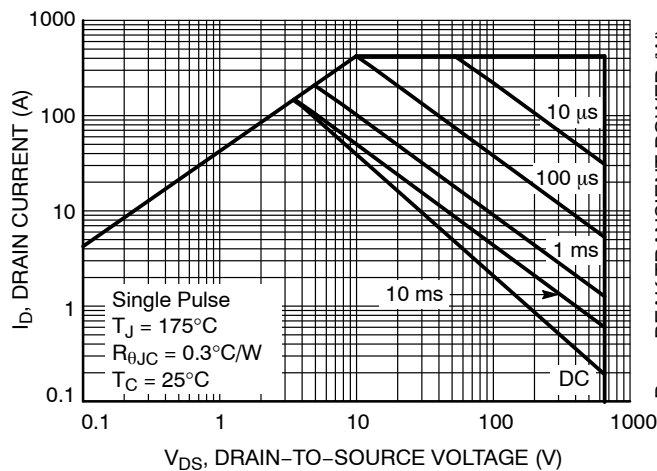


Figure 11. Safe Operating Area

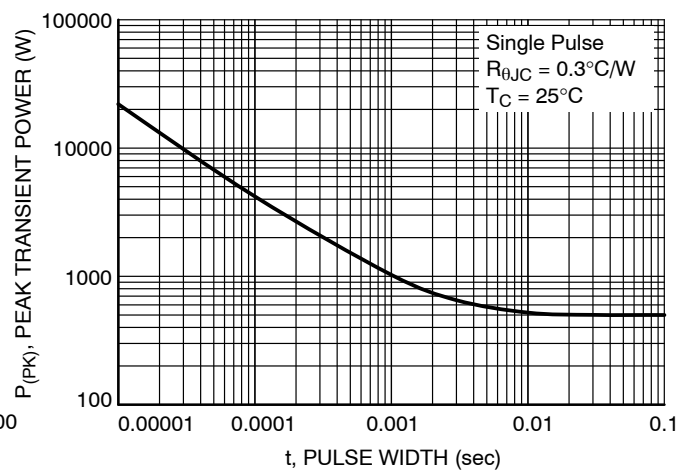


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

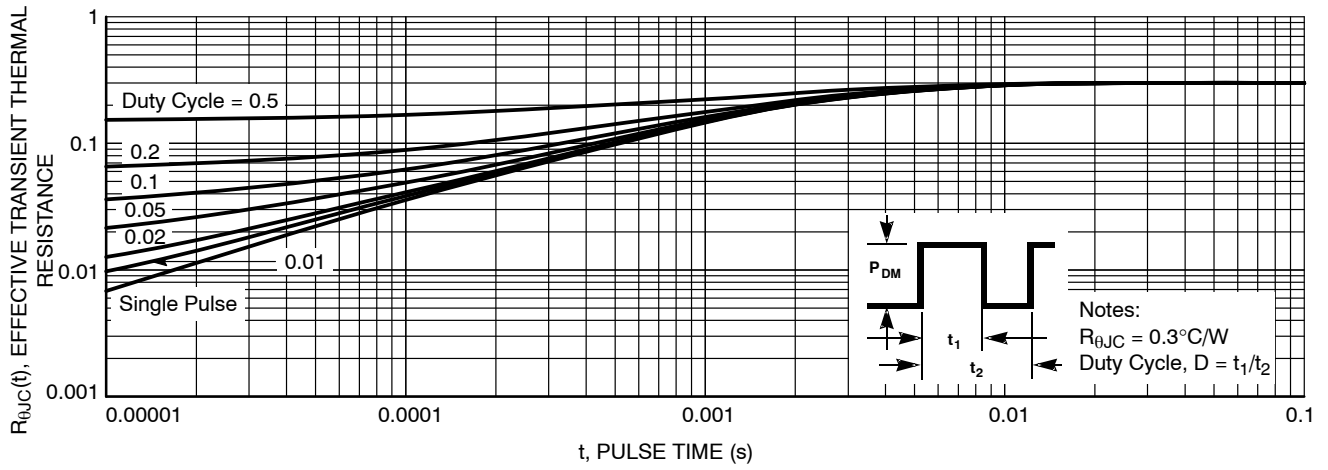
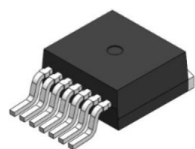


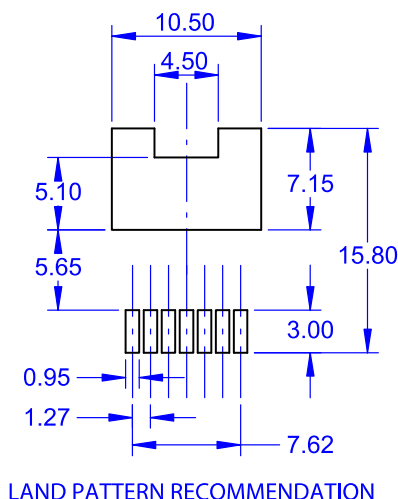
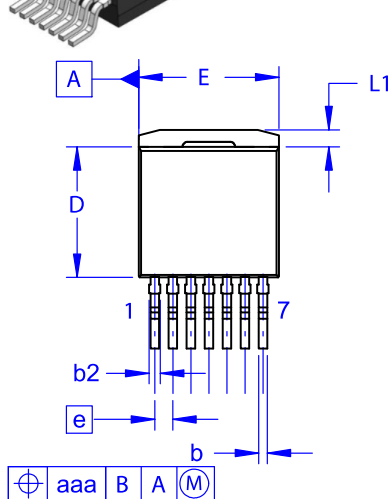
Figure 13. Junction-to-Case Transient Thermal Response Curve

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**D<sup>2</sup>PAK7 (TO-263-7L HV)**  
CASE 418BJ  
ISSUE B

DATE 16 AUG 2019



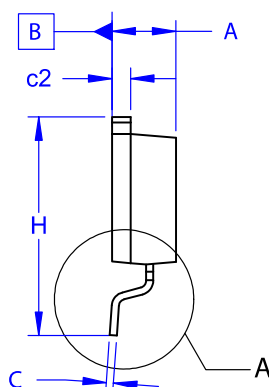
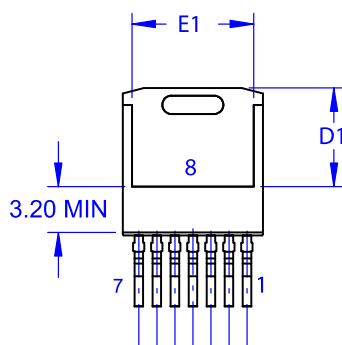
## NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.

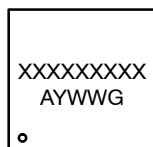
△ OUT OF JEDEC STANDARD VALUE.  
D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.

E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
c	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
E	9.70	9.90	10.20
E1	7.15	7.65	8.15
e	~	1.27	~
H	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25

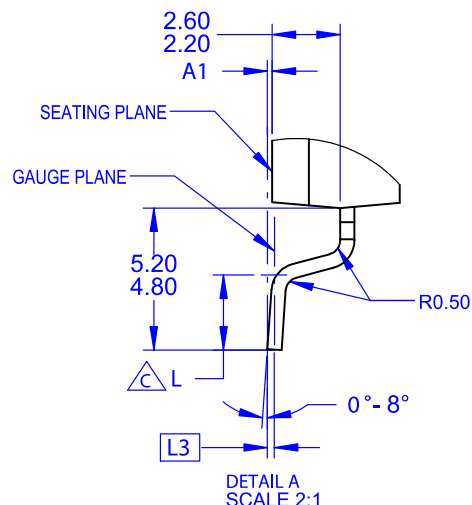


## GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



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